Docea Power Unveils New Release of Aceplorer and AceThermalModeler, Enables Dynamic Power and Thermal Management Analysis with Real Use Cases

Demos at DATE, March 19 - 21, Grenoble - France

Grenoble, France and San Jose, CA – March 14, 2013 – Docea Power, the design-for-low-power company that delivers software solutions for power and thermal analysis at the architectural level, today announced new releases of Aceplorer 3.1 and AceThermalModeler 2.0.

Aceplorer 3.1 features a new solver for coupled power and thermal transient simulations featuring 1000x performance gains over the previous versions and a communication protocol enabling the co-simulation of Aceplorer models with virtual platforms and performance analysis tools. AceThermalModeler 2.0 (ATM) improves its usability.

Aceplorer is Docea Power’s system-level power and thermal modeling and simulation software for early architecture exploration, architecture validation and power budget tracking. AceThermalModeler generates compact thermal models for System on Chips (SoCs), 3D ICs, Systems in Package (SiPs) or complete board.

Docea Power will be demonstrating its new software releases at DATE (Design Automation and Test) 2013 in Grenoble from March 19 to 21 on booth #41.

“With the combination of higher power density and smaller form factors, the limit of what current packaging solutions can dissipate is being reached for many devices. A high junction temperature or a high case temperature can quickly limit access to full performance and hamper the user’s experience,” noted Ghislain Kaiser, Docea Power CEO. “Our latest releases, give systems architects better tools to optimize their design and support a collaborative framework among system architects, packaging designers, thermal experts, software developers and SoC designers.”

What’s New

Aceplorer 3.1 features a fast solver for coupled power and thermal simulations with 1000x performance gains over the previous version. It also features a communication protocol for 3rd party tools that enables co-simulation with timed virtual platforms or performance analysis tools. Co-simulation of timed virtual platforms and Aceplorer models allow users to simulate dynamic power and thermal management strategies using real use cases where simulation duration ranges from a few seconds to tens of minutes.

Docea’s dynamic power and thermal management simulations allow system architects to scale the operating point in the performance model with power and temperature feedback provided by Aceplorer’s virtual power model during simulation.

AceThermalModeler 2.0 improves usability and has an enhanced graphical user interface to ease the modeling. Models generated with AceThermalModeler are imported in Aceplorer for transient and steady state thermal response to use case based power stimuli.
About Docea Power
Docea Power develops and commercializes a new generation of methodology and tools for enabling faster more reliable power and thermal modeling at the system level. Based on its Aceplorer platform, the Docea Power solution uses a consistent approach for executing architecture exploration and optimizing power and thermal behavior of electronic systems at an early stage of an electronic design project. The company has offices near Grenoble, France, and in San Jose, California, USA, and sales offices in Japan and Korea. For more information, please visit www.doceapower.com.

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